

Vishay Siliconix

RoHS COMPLIANT

HALOGEN

FREE

Dual P-Channel 12-V (D-S) MOSFET

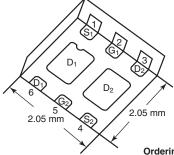
PRODUCT SUMMARY					
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A)	Q _g (Typ.)		
	0.061 at V _{GS} = - 4.5 V	- 4.5 ^a			
- 12	0.081 at V _{GS} = - 2.5 V	- 4.5 ^a	8.2 nC		
	0.115 at V _{GS} = - 1.8 V	- 4.5 ^a			

FEATURES

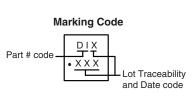
- Halogen-free According to IEC 61249-2-21
- TrenchFET[®] Power MOSFET
- New Thermally Enhanced PowerPAK[®] SC-70 Package
 - Small Footprint Area - Low On-Resistance

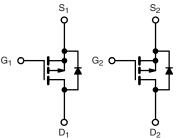
APPLICATIONS

 Load Switch, PA Switch and Battery Switch for Portable Devices
Station Stationary St



PowerPAK SC-70-6 Dual





Ordering Information: SiA913ADJ-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET P-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 12	V	
Gate-Source Voltage		V _{GS}	± 8		
Continuous Drain Current (T _J = 150 °C)	$T_{C} = 25 \text{ °C}$ $T_{C} = 70 \text{ °C}$	I _D	- 4.5 ^a - 4.5 ^a	_	
	T _A = 25 °C T _A = 70 °C		- 4.3 ^{b, c} - 3.8 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	- 15		
Continuous Source-Drain Diode Current	T _C = 25 °C T _A = 25 °C	I _S	- 4.5 ^a - 1.6 ^{b, c}	_	
Maximum Power Dissipation	T _C = 25 °C T _C = 70 °C	P _D	6.5 5	w	
	T _A = 25 °C T _A = 70 °C		1.9 ^{b, c} 1.2 ^{b, c}		
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 150	°C		
Soldering Recommendations (Peak Temperatur	Ť.	260			

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, f}	t ≤ 5 s	R _{thJA}	52	65	°C/W		
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	12.5	16	0/11		

Notes:

a. Package limited.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. See Solder Profile (<u>www.vishay.com/ppg?73257</u>). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

f. Maximum under Steady State conditions is 110 °C/W.

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SPECIFICATIONS $T_J = 25 \degree C$, unless oth	erwise noted		-				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static				-	1	1		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = -250 \mu A$				V		
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 3.1		mV/°C		
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	2 .		2.4				
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \ \mu A$	- 0.4		- 1	V		
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V$, $V_{GS} = \pm 8 V$			± 100	nA		
Zero Gate Voltage Drain Current	1200	$V_{DS} = -12 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1	114		
Zero Gale Voltage Drain Gurrent	I _{DSS}	V_{DS} = - 12 V, V_{GS} = 0 V, T_{J} = 55 °C			- 10	μΑ		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le$ - 5 V, V_{GS} = - 4.5 V	- 10			Α		
		V _{GS} = - 4.5 V, I _D = - 3.6 A		0.050	0.061	Ω		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 3.2 A		0.066	0.081			
		V _{GS} = - 1.8 V, I _D = - 1 A		0.093	0.115			
Forward Transconductance ^a	g _{fs}	V _{DS} = - 6 V, I _D = - 3.6 A		11		S		
Dynamic ^b						1		
Input Capacitance	C _{iss}			590		pF		
Output Capacitance	C _{oss}	V _{DS} = - 6 V, V _{GS} = 0 V, f = 1 MHz		280				
Reverse Transfer Capacitance	C _{rss}			250				
		$V_{DS} = -6 V_{V} V_{CS} = -8 V_{V} I_{D} = -4.5 A$		13.1	20	<u> </u>		
Total Gate Charge	Qg			8.2	12.5	nC		
Gate-Source Charge	Q _{gs}	V _{DS} = - 6 V, V _{GS} = - 4.5 V, I _D = - 4.5 A		1.2	-			
Gate-Drain Charge	Q _{gd}			2.8				
Gate Resistance	R _g	f = 1 MHz		10		Ω		
Turn-On Delay Time	t _{d(on)}			20	30	- ns		
Rise Time	tr	$V_{DD} = -6 V, R_1 = 1.6 \Omega$		25	40			
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 3.8 A, V_{GEN} = - 4.5 V, R_q = 1 Ω		30	45			
Fall Time	t _f	C C		20	30			
Turn-On Delay Time	t _{d(on)}			8	15			
Rise Time	t _r	$V_{DD} = -6 V, R_1 = 1.6 \Omega$		12	20			
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 3.8 A, V_{GEN} = - 8 V, R_g = 1 Ω		25	40			
Fall Time	t _f	5		18	30			
Drain-Source Body Diode Characteris	tics							
Continuous Source-Drain Diode Current		T _C = 25 °C			- 4.5			
Pulse Diode Forward Current	I _{SM}			1	10	A		
Body Diode Voltage	V _{SD}	I _S = - 3.8 A, V _{GS} = 0 V		- 0.85	- 1.2	V		
Body Diode Reverse Recovery Time	t _{rr}			30	60	ns		
Body Diode Reverse Recovery Charge	Q _{rr}			12	24	nC		
Reverse Recovery Fall Time	ta	$I_F = -3.8 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, \text{ T}_J = 25 ^\circ\text{C}$		16				
Reverse Recovery Rise Time	t _a			14		ns		

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

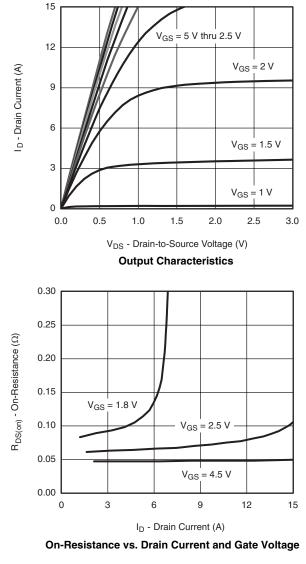
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

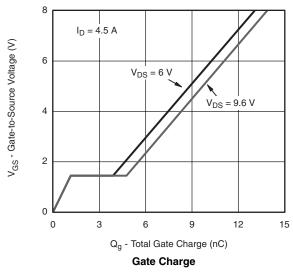


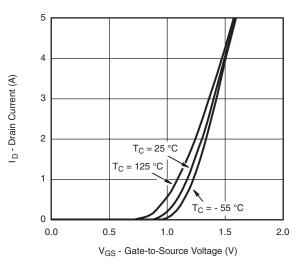


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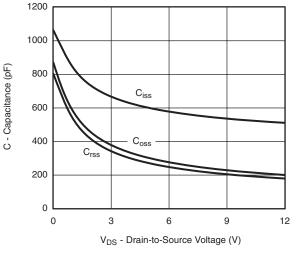
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



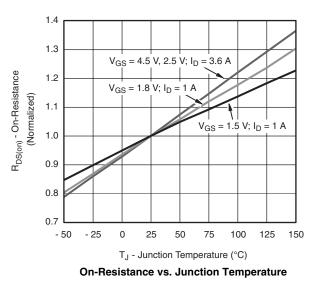




Transfer Characteristics





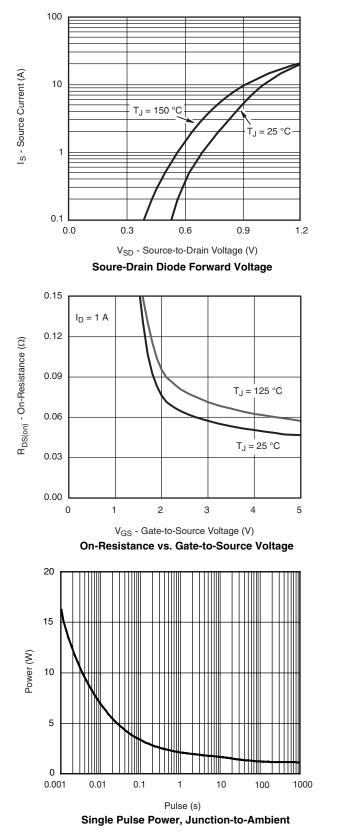


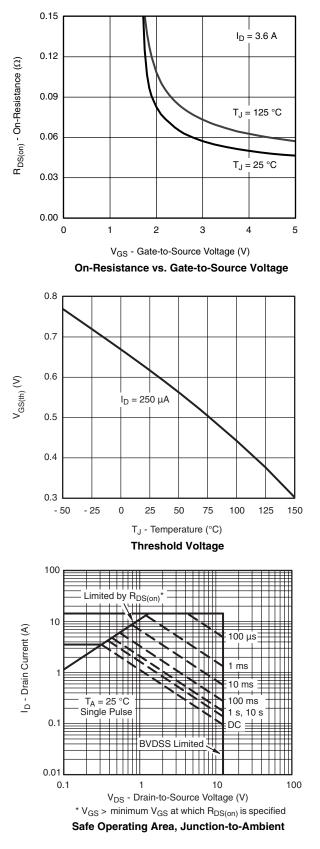
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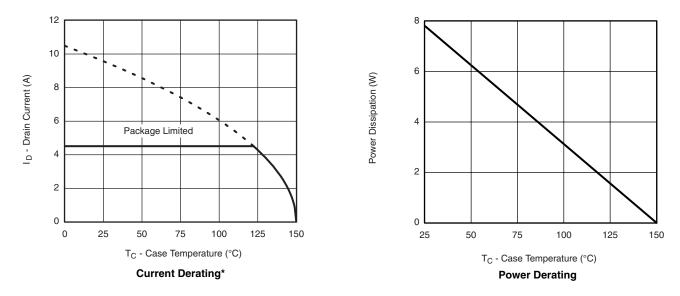






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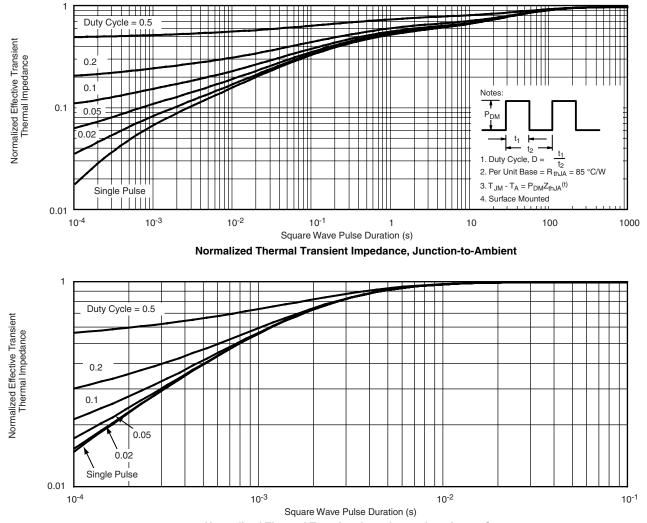


* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?64723.



PowerPAK[®] SC70-6L

VISHA

b PIN2 PIN1 PIN3 _ ₹



b

PIN3

__ ₿

PIN2

PIN1

¥

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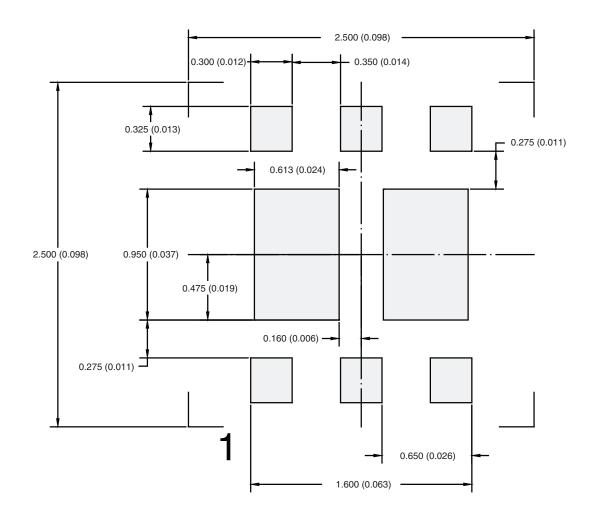
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Application Note 826

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RECOMMENDED PAD LAYOUT FOR PowerPAK® SC70-6L Dual



Dimensions in mm (inches)

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